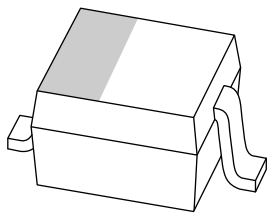


# DATA SHEET



**BAP51-03**

General purpose PIN diode

Product specification  
Supersedes data of 1999 Aug 16

2004 Feb 11



# General purpose PIN diode

# BAP51-03

### FEATURES

- Low diode capacitance
- Low diode forward resistance.

### APPLICATIONS

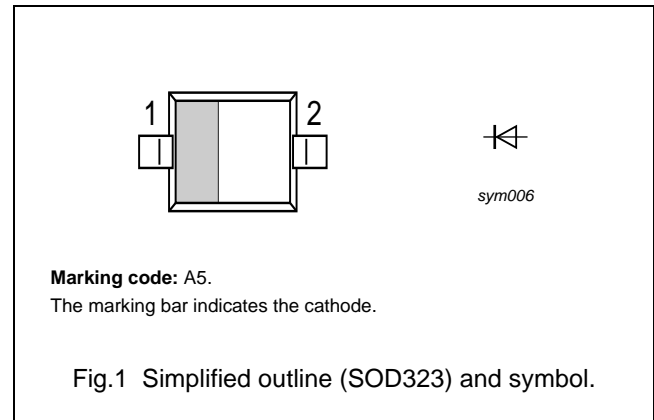
- General RF applications.

### DESCRIPTION

General purpose PIN diode in a SOD323 small plastic SMD package.

### PINNING

PIN	DESCRIPTION
1	cathode
2	anode



### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BAP51-03	-	plastic surface mounted package; 2 leads	SOD323

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_R$	continuous reverse voltage		-	50	V
$I_F$	continuous forward current		-	50	mA
$P_{tot}$	total power dissipation	$T_S = 90\text{ °C}$	-	500	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-65	+150	°C

## General purpose PIN diode

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**ELECTRICAL CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_F$	forward voltage	$I_F = 50\text{ mA}$	–	0.95	1.1	V
$V_R$	reverse voltage	$I_R = 10\text{ }\mu\text{A}$	50	–	–	V
$I_R$	reverse current	$V_R = 50\text{ V}$	–	–	100	nA
$C_d$	diode capacitance	$V_R = 0; f = 1\text{ MHz}$	–	0.4	–	pF
		$V_R = 1\text{ V}; f = 1\text{ MHz}$	–	0.3	0.55	pF
		$V_R = 5\text{ V}; f = 1\text{ MHz}$	–	0.2	0.35	pF
$r_D$	diode forward resistance	$I_F = 0.5\text{ mA}; f = 100\text{ MHz}; \text{note 1}$	–	5.5	9	$\Omega$
		$I_F = 1\text{ mA}; f = 100\text{ MHz}; \text{note 1}$	–	3.6	6.5	$\Omega$
		$I_F = 10\text{ mA}; f = 100\text{ MHz}; \text{note 1}$	–	1.5	2.5	$\Omega$
$\tau_L$	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}; R_L = 100\text{ }\Omega$ ; measured at $I_R = 3\text{ mA}$	–	550	–	ns

**Note**

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

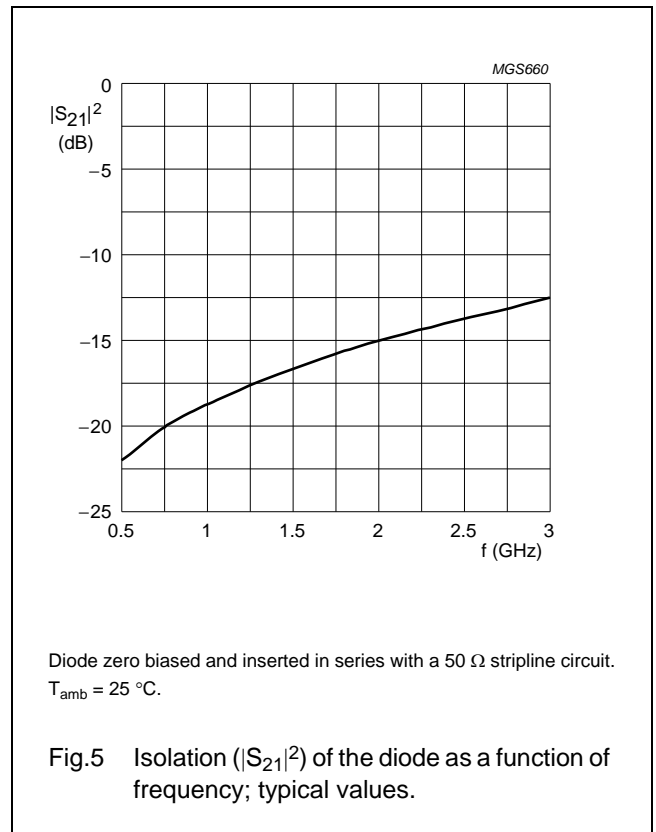
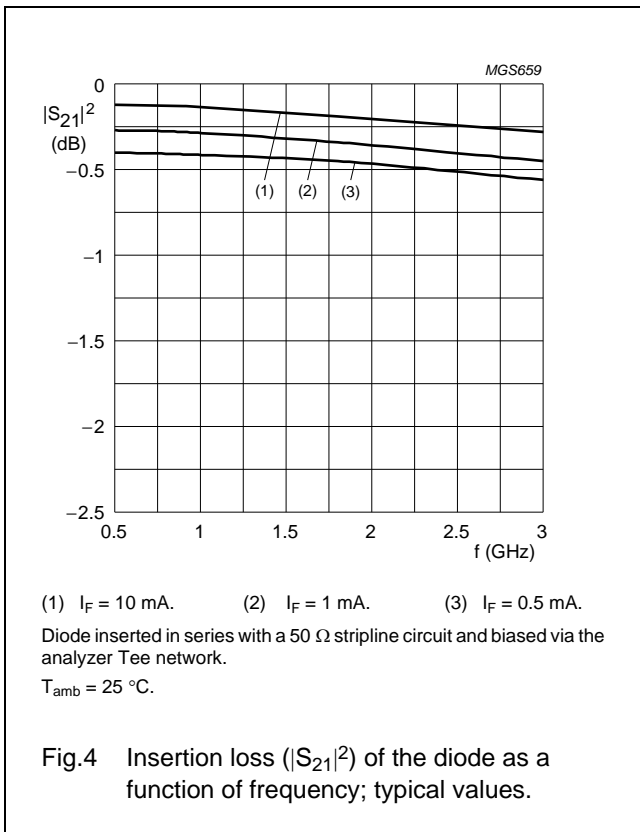
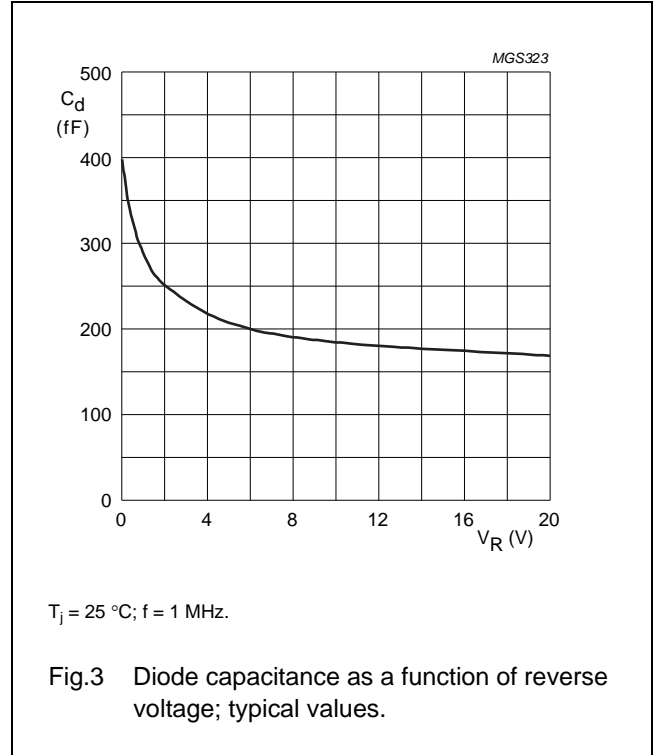
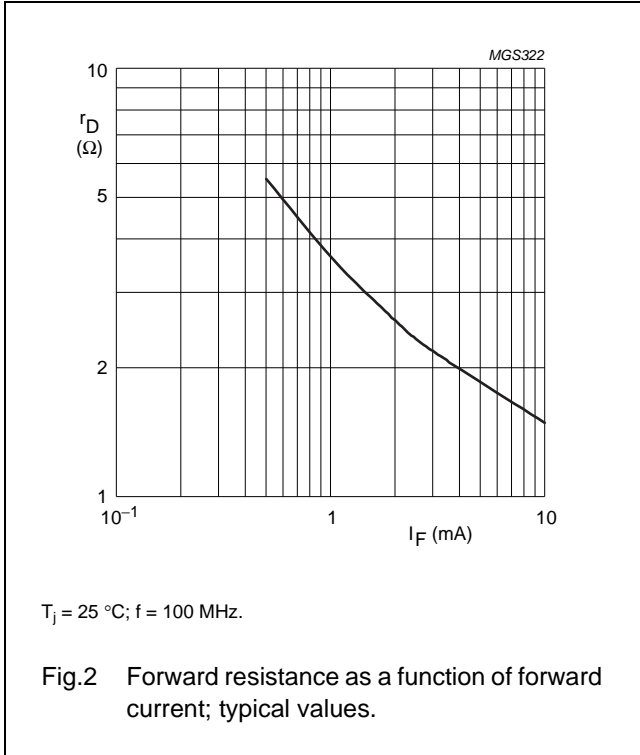
**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th(j-s)}$	thermal resistance from junction to soldering point	120	K/W

General purpose PIN diode

BAP51-03

GRAPHICAL DATA



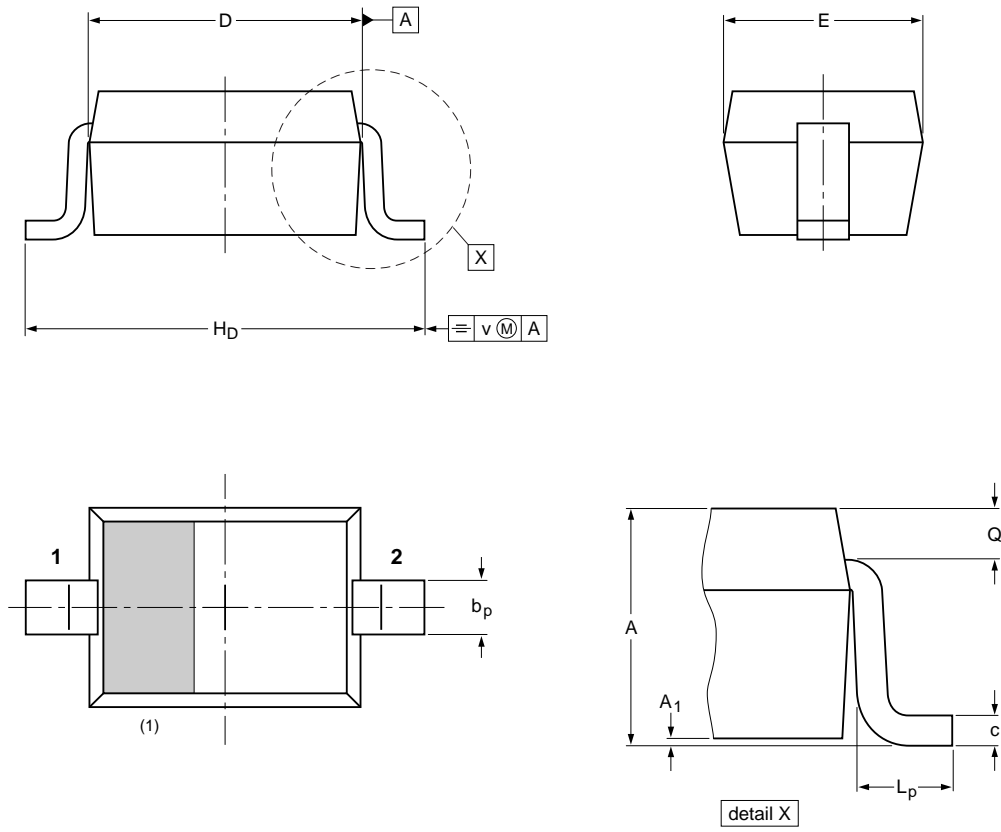
General purpose PIN diode

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PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	H <sub>D</sub>	L <sub>p</sub>	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOD323			SC-76		<del>03-12-17</del> 06-03-16

# General purpose PIN diode

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## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

### Notes

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## General purpose PIN diode

## BAP51-03

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## **Customer notification**

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## **Contact information**

For additional information please visit: <http://www.nxp.com>

For sales offices addresses send e-mail to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

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